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**Recommendation for Examiner's Amendment**

**U.S. Application No. 09/871,671**

Please amend claim 26 as follows:

26. (Thrice Amended) A method of manufacturing a semiconductor device, comprising:

mounting at least one semiconductor chip having bumps on at least a region of a surface of a flexible substrate; and

bending said substrate into a cylindrical form[[,]];

wherein said chip is bent; and

wherein a diameter of the cylindrical substrate is smaller than a width of the at least one semiconductor chip.